

ABSTRACT

A multi-layer laminated circuit board 10A of the present invention is formed by laminating together a multi-layer transformer 10, a multi-layer part sheet 30 formed with a multi-layer part, and a wiring sheet 50 formed with a circuit pattern. The multi-layer transformer 10 is incorporated into the multi-layer laminated circuit board 10A, and therefore a package for the multi-layer transformer 10 is omitted, and the wiring between the multi-layer transformer 10 and other components is reduced to a minimum.